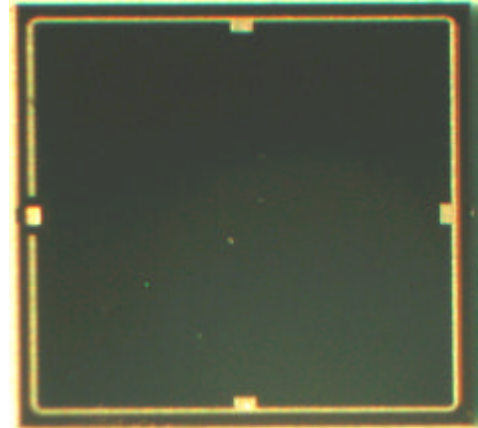


QSD-3430

SILICON PIN PHOTODIODE

COMMON CATHODE TYPE PIN PHOTO DIODE.
APPLICABLE SURFACE BONDING.

- **DIE SIZE** 4.30mm × 4.30mm
- **DIE THICKNESS** 400 ± 15μm
- **METALLIZATION**
 - TOP Al
 - BOTTOM Au or None
- **PASSIVATION** Silicon Nitride
- **BONDING PAD SIZE**
 - ANODE(TOP) 150μm × 200μm
 - CATHODE(BOTTOM) 100μm × 180μm



• **ABSOLUTE MAXIMUM RATINGS (Ta= 25° C)**

Parameter	Symbol	Maximum rating	Unit
Reverse Breakdown Voltage	B _{VR}	30	V
Junction Temperature	T _J	150	°C

• **ELECTRICAL / OPTICAL CHARACTERISTICS (Ta= 25° C)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Open Circuit Voltage	V _{OP}	Note(1)	0.3	0.4		V
Short Circuit Current	I _{SC}	Note(1)	75	90		μA
Spectrum Sensitivity	λ		450 ~ 1,100			nm
Peak Sensing Wavelength	λ _P			880		nm
Forward Voltage	V _F	I _F =100 mA		1.4	1.5	V
Dark Current	I _D	V _R =10V		10	50	nA
Reverse Breakdown Voltage	B _{VR}	I _R =10μA	40	80		V

Note(1): Parallel light of 1,000 Lux illumination is applied by a Tungsten lamp of 2856k.